

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1tc2922cf-3.3#trpbfb

(Engineering Calculation)

TSSOP

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**TOTAL MASS (g) : 0.074666**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.005518	1000000	73902.1171875		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.024098	962000	322742.5		
		Iron (Fe)	7439-89-6	0.000000	0	0		
		Phosphorus (P)	7723-14-0	0.000000	0	0		
		Zinc (Zn)	7440-66-6	0.000000	0	0		
		Nickel (Ni)	7440-02-0	0.000751	30000	10058.0810547		
		Silicon (Si)	7440-21-3	0.000163	1500	508.93081665		
		Magnesium (Mg)	7439-95-4	0.000038	1500	508.93081665		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.025050</b>	<b>1000000</b>	<b>335492.5625</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.001770	1000000	23709.8671875		
		<b>External Plating Total:</b>				<b>0.001770</b>	<b>1000000</b>	<b>23709.8671875</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000000	0	0		
<b>Internal Plating Total:</b>				<b>0.000000</b>	<b>0</b>	<b>0</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001409	750000	18870.6191406		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000470	250000	6294.67041016		
<b>Die Attach Total:</b>				<b>0.001879</b>	<b>1000000</b>	<b>25165.2890625</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.005414	135000	72509.2421875		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.034486	860000	461868.09375		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000201	5000	2691.97631836		
		<b>Encapsulation Total:</b>				<b>0.040101</b>	<b>1000000</b>	<b>537069.3125</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000348	1000000	4660.73486328		
					<b>TOTAL MASS (g) :</b>	<b>0.074666</b>		